Test Points

SCL0-TG  SCL1-TG  SCL2-TG  SCL3-TG
SCL4-TG  SCL5-TG  SCL6-TG  SCL7-TG
SDA0-TG  SDA1-TG  SDA2-TG  SDA3-TG
SDA4-TG  SDA5-TG  SDA6-TG  SDA7-TG

Vref  ON/OFF  Vsource

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Sockets

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DC Power Layout
You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.
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